

650V N-SJ ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

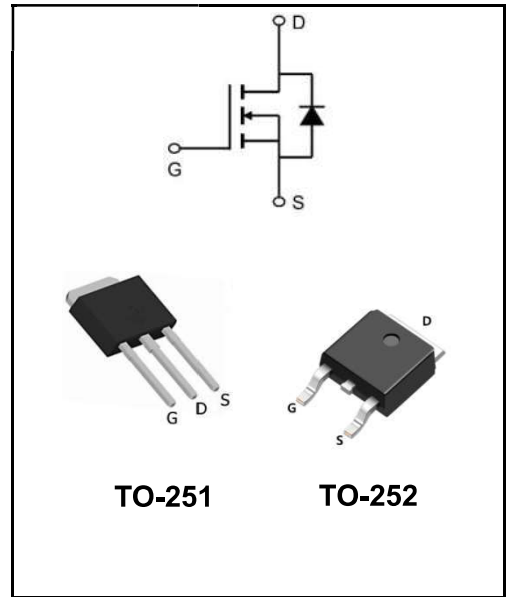
I_D	4A
V_{DSS}	650V
R_{DS(on)-typ(@V_{GS}=10V)}	< 1100mΩ (Type:950mΩ)

Features

- ◆ Low RDS(on) & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Application

- ◆ Lighting
- ◆ Server power supply
- ◆ Telecom
- ◆ Solar inverter


Product Specification Classification

Part Number	Package	Marking	Pack
YFWJ4N65AD	TO-252	YFW J4N65AD XXXXX	2500PCS/Tape
YFWJ4N65AMJ	TO-251	YFW J4N65AMJ XXXXX	4000PCS/Tape

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	650	V
Gate - Source Voltage	V_{GS}	±30	V
Continuous Drain Current at T _C =25°C	I_{D(DC)}	4	A
Continuous Drain Current at T _C =100°C		2.5	A
Pulsed Drain Current(Note1)	I_{DM} (pluse)	16	A
Power Dissipation T _C =25°C	P_D	41	W
Single Pulse Avalanche Energy (Note2)	E_{AS}	27	mJ
Avalanche current(Note 1)	I_{AR}	0.7	A
Repetitive Avalanche energy t _{AR} limited by T _{Jmax} (Note 1)	E_{AR}	0.1	mJ
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} =0...480 V, I _{SD} ≤I _D	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_J , T_{STG}	-55 to 150	°C
Thermal Resistance, Junction-to-Case (Maximum)	R_{θJC}	3.0	°C/W
Thermal Resistance, Junction-to-ambient (Maximum)	R_{θJA}	62	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	BV_{DSS}	650	-	-	V
Zero Gate Voltage Drain Current	$V_{DS}=650V, V_{GS}=0V, T_C=25^\circ C$	I_{DSS}	-	-	1	μA
	$V_{DS}=650V, V_{GS}=0V, T_C=125^\circ C$		-	-	50	
Gate to Body Leakage Current	$V_{GS}=\pm 20V$	I_{GSS}	-	-	± 100	nA
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	$V_{GS(th)}$	3	-	4	V
Drain-Source On-State Resistance	$V_{GS}=10V, I_D=2A$	$R_{DS(ON)}$	-	950	1100	m Ω
Input Capacitance	$V_{DS}=50V$ $V_{GS}=0V$ $f=1MHz$	C_{iss}	-	304	-	μF
Output Capacitance		C_{oss}	-	18	-	
Reverse Transfer Capacitance		C_{rss}	-	0.6	-	
Total Gate Charge	$V_{DS}=480V$ $I_D=4A$ $V_{GS}=10V$	Q_g	-	8.8	1.2	nC
Gate-Source Charge		Q_{gs}	-	2.3	-	
Gate-Drain Charge		Q_{gd}	-	4	-	
Turn-on delay time	$V_{DD}=380V$ $I_D=2.5A$ $R_G=5\Omega$ $V_{GS}=10V$	$t_{d(on)}$	-	8	-	ns
Turn-on Rise Time		T_r	-	4	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	52	70	
Turn-on Fall Time		t_f	-	9	18	
Source-drain current(Body Diode)	$T_C=25^\circ C$	I_{SD}	-	-	4	A
Pulsed Source-drain current(Body Diode)		I_{SDM}	-	-	16	A
Forward On Voltage	$V_{GS}=0V, I_{SD}=4A, T_J=25^\circ C$	V_{SD}	-	0.9	1.2	V
Reverse Recovery Time	$I_F=2A, di_{SD}/dt=100A/\mu s,$ $T_J=25^\circ C$	t_{rr}	-	200	-	ns
Reverse Recovery Charge		Q_{rr}	-	0.6	-	nC
Peak reverse recovery current		I_{rrm}	-	6	-	A

Ratings and Characteristic Curves

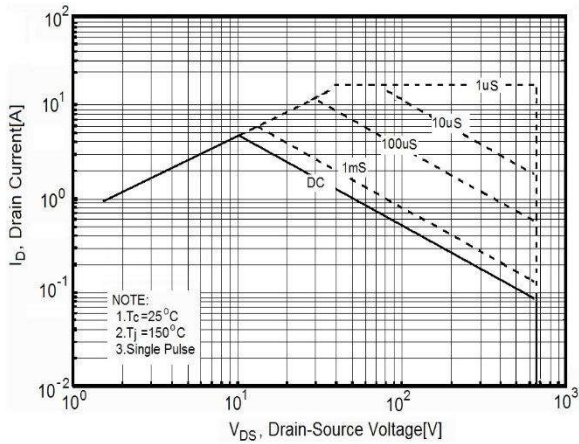


Figure1. Safe operating area

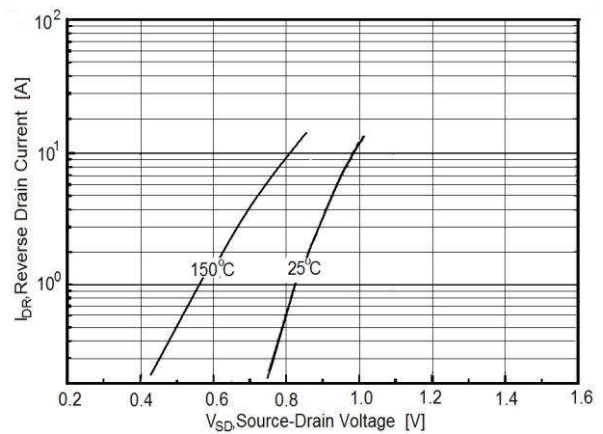


Figure2. Source-Drain Diode Forward Voltage

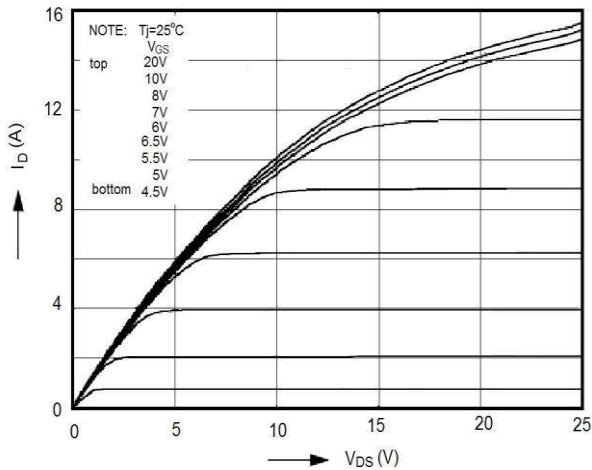


Figure3. Output characteristics

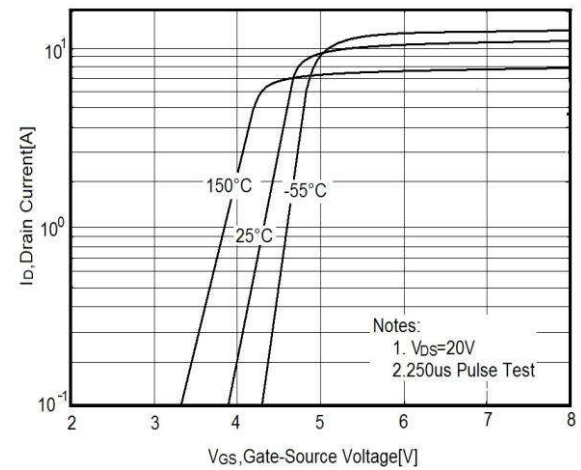


Figure4. Transfer characteristics

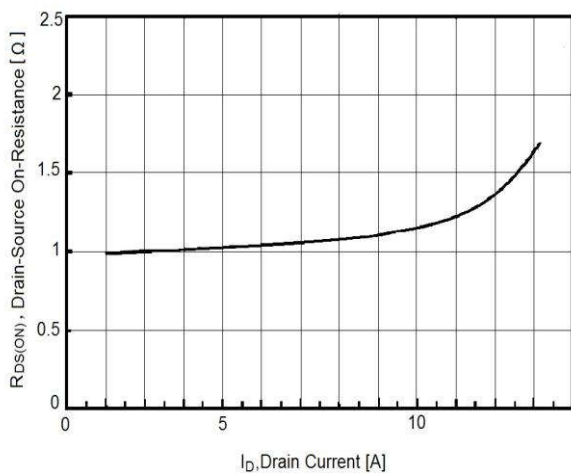


Figure5. Static drain-source on resistance

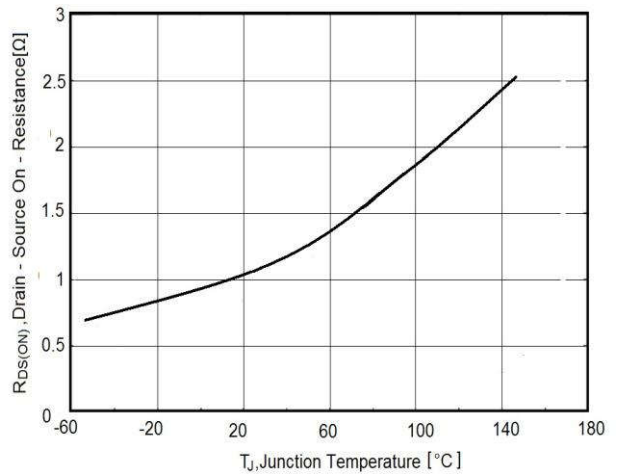


Figure6. RDS(ON) vs Junction Temperature

Ratings and Characteristic Curves

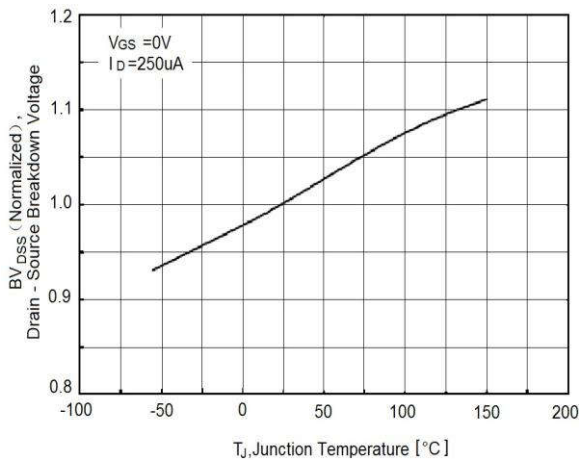


Figure7. BV_{DSS} vs Junction Temperature

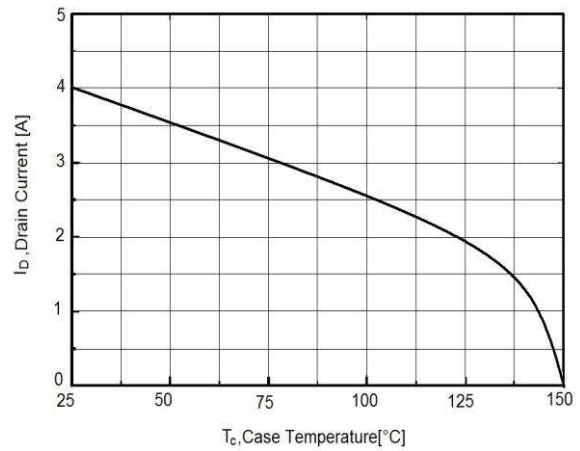


Figure8. Maximum I_D vs Junction Temperature

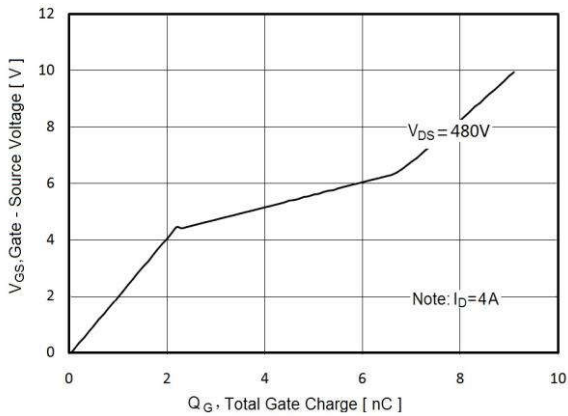


Figure9. Gate charge waveforms

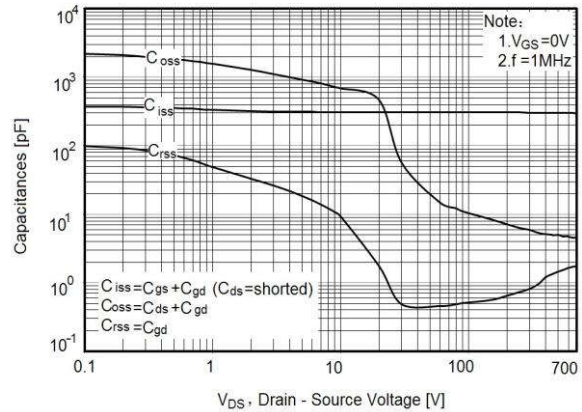


Figure10. Capacitance

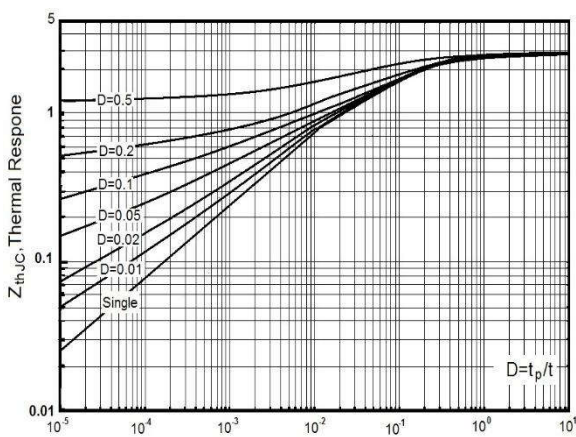


Figure11. Transient Thermal Impedance

Test circuits and waveforms

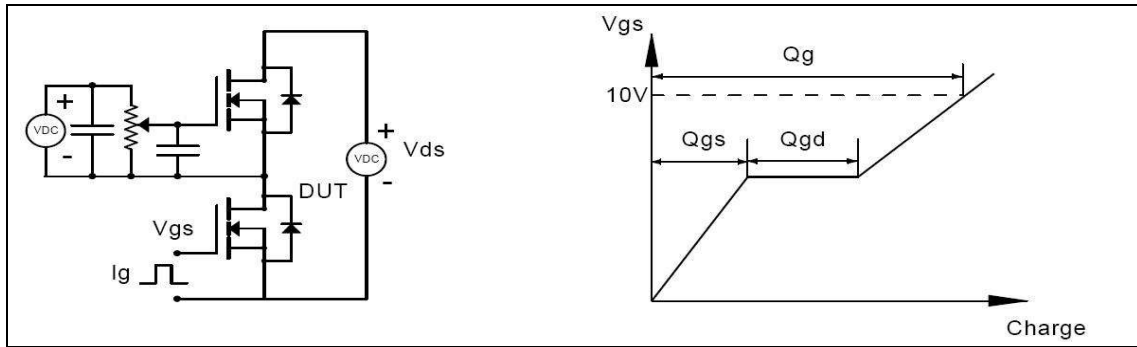


Figure 1, Gate charge test circuit & waveform

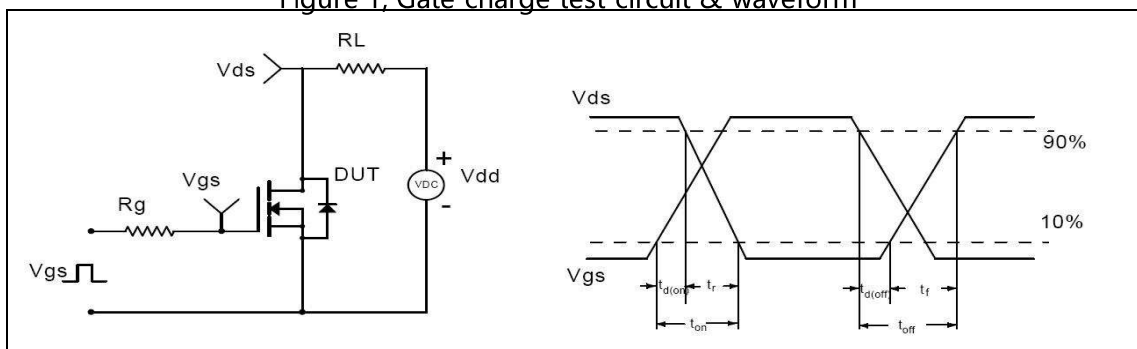


Figure 2, Switching time test circuit & waveforms

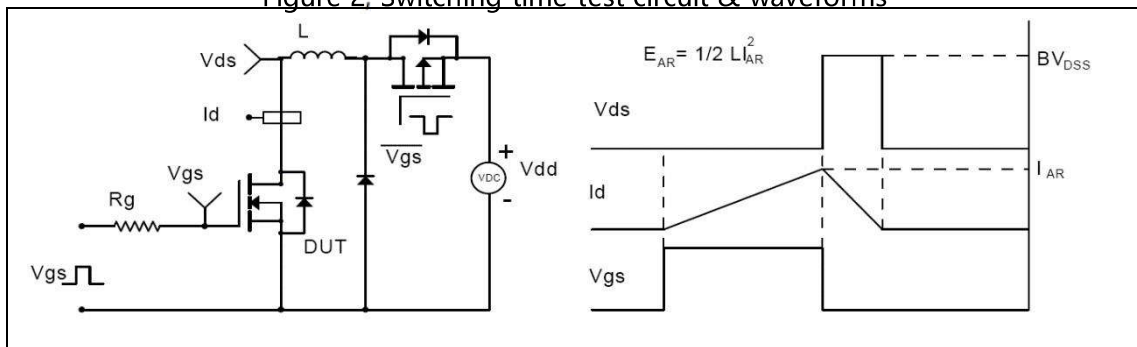


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

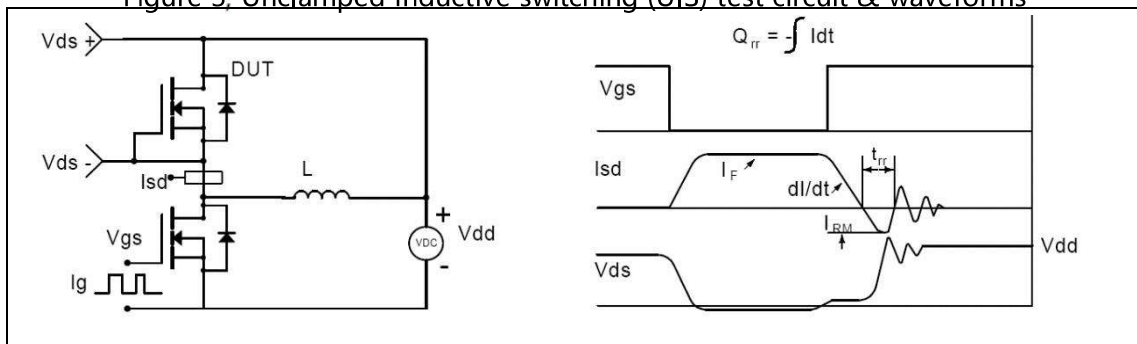
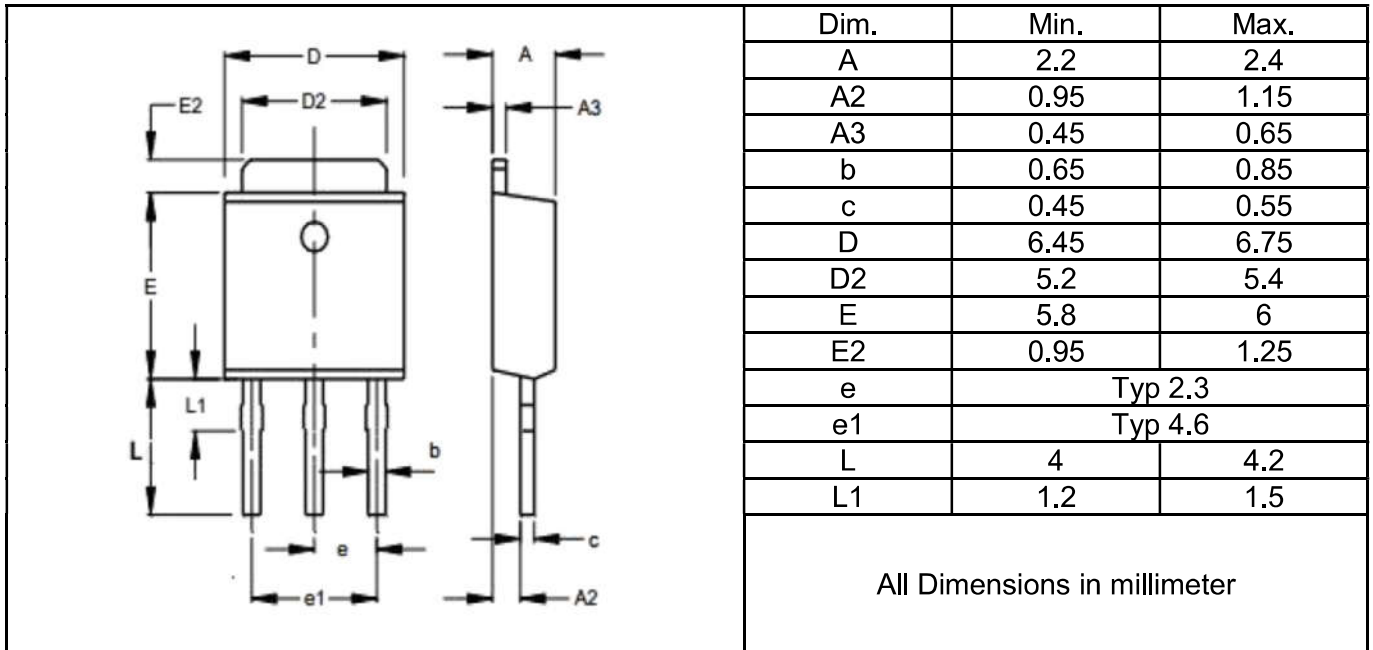


Figure 4, Diode reverse recovery test circuit & waveforms

Package Outline Dimensions Millimeters

TO-251



TO-252

